

9/10/3

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PTO-1449	Application No. <i>To be Assigned</i>	Applicant(s) <i>Howard, et al.</i>
Information Disclosure Citation In an Application	Docket Number TI-36332 (032350.B531)	Group Art Unit <i>To be Assigned</i> <i>2815</i>
		Filing Date Sept. 10, 2003

U.S. PATENT DOCUMENTS

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DOCUMENT (Including Author, Title, Source, and Pertinent Pages)

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R	"Challenges in High Yield, Fine Pitch Solder Ball Attachment", by Ivy Qin, et al., SEMI - Semicon Singapore - Semiconductor Packaging Conference, pp. 1-10	05/2001
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EXAMINER	DATE CONSIDERED
<i>[Signature]</i>	9/13/04

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